Lattice Semiconductor Corporation - LFXP15C-3FN388I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15000
Total RAM Bits	331776
Number of I/O	268
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	388-BBGA
Supplier Device Package	388-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp15c-3fn388i

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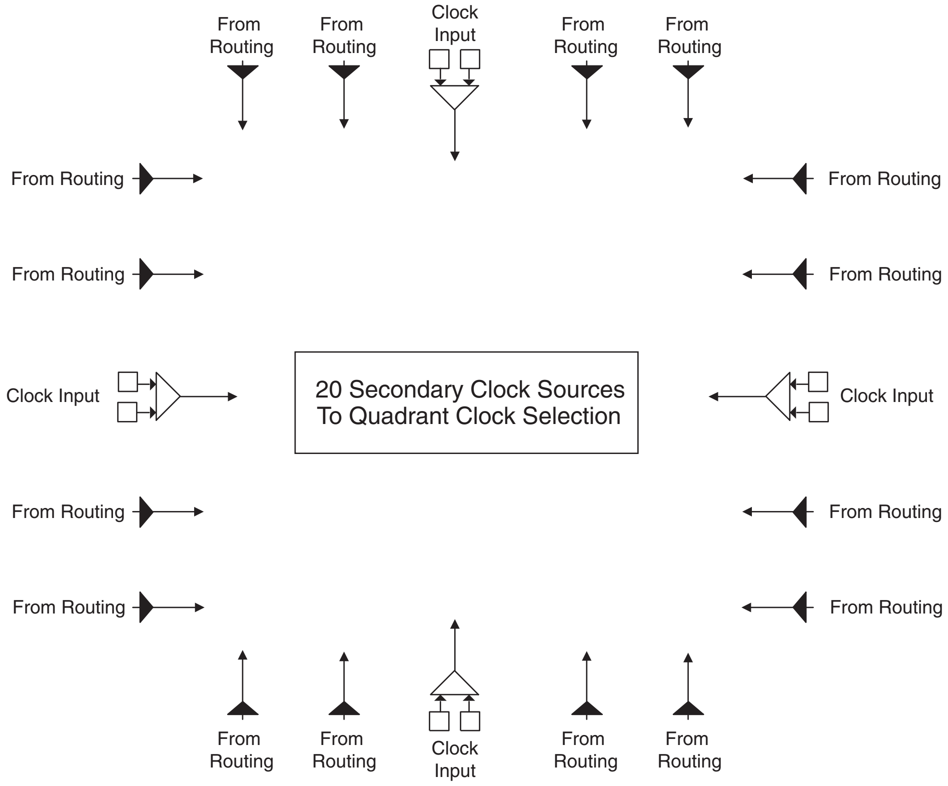
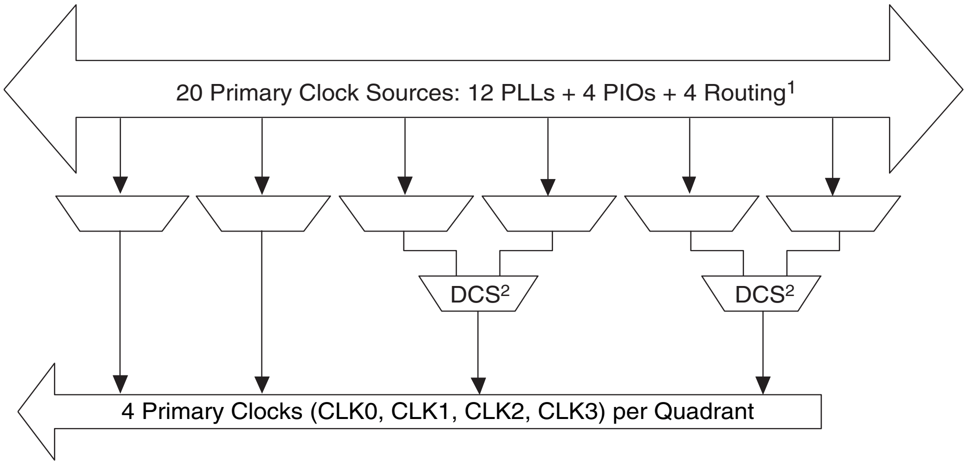
Figure 2-6. Secondary Clock Sources



Clock Routing

The clock routing structure in LatticeXP devices consists of four Primary Clock lines and a Secondary Clock network per quadrant. The primary clocks are generated from MUXs located in each quadrant. Figure 2-7 shows this clock routing. The four secondary clocks are generated from MUXs located in each quadrant as shown in Figure 2-8. Each slice derives its clock from the primary clock lines, secondary clock lines and routing as shown in Figure 2-9.

Figure 2-7. Per Quadrant Primary Clock Selection



1. Smaller devices have fewer PLL related lines.
2. Dynamic clock select.

Figure 2-8. Per Quadrant Secondary Clock Selection

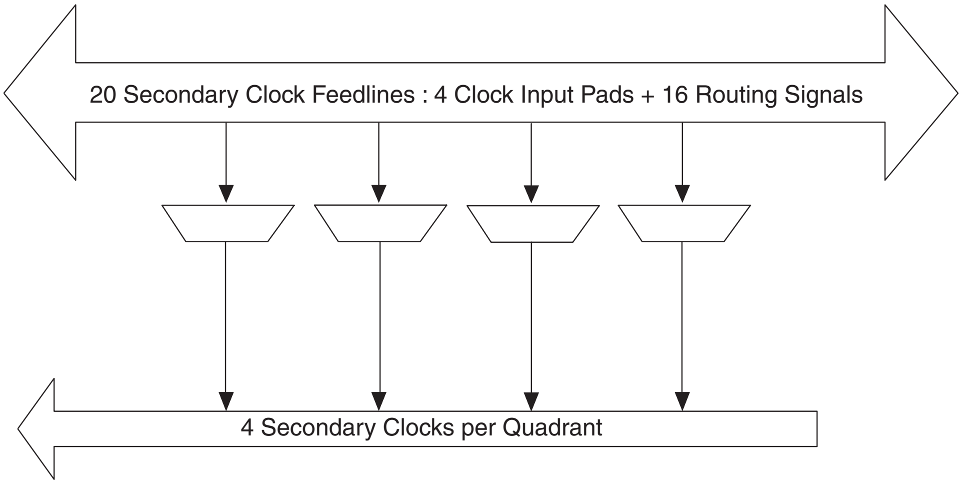
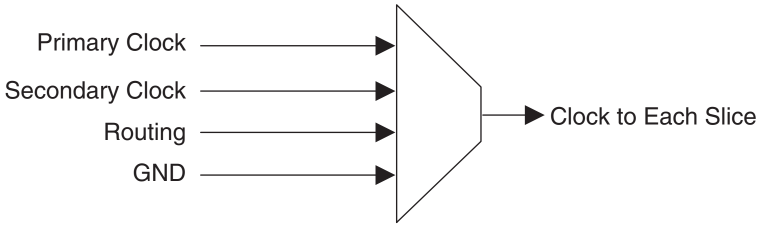


Figure 2-9. Slice Clock Selection



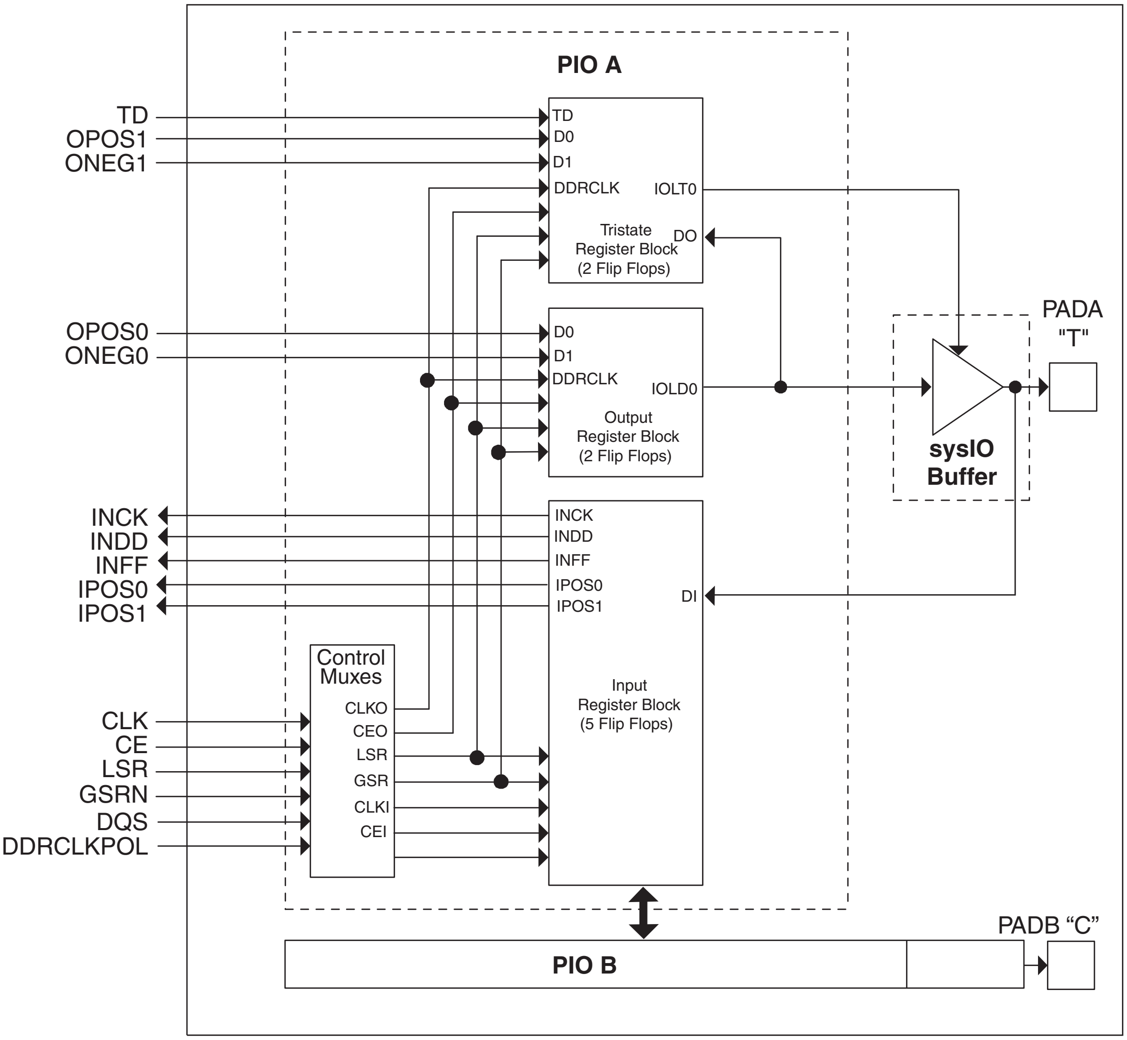
sysCLOCK Phase Locked Loops (PLLs)

The PLL clock input, from pin or routing, feeds into an input clock divider. There are three sources of feedback signals to the feedback divider: from CLKOP (PLL internal), from clock net (CLKOP or CLKOS) or from a user clock (PIN or logic). There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-17. PIC Diagram



In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

Table 2-8. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Nom.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVCMOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVCMOS25	4mA, 8mA, 12mA 16mA, 20mA	2.5
LVCMOS18	4mA, 8mA, 12mA 16mA	1.8
LVCMOS15	4mA, 8mA	1.5
LVCMOS12	2mA, 6mA	1.2
LVCMOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVCMOS15, Open Drain	4mA, 8mA	—
LVCMOS12, Open Drain	2mA. 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS[1]	N/A	2.5
LVPECL[1]	N/A	3.3

1. Emulated with external resistors.

Hot Socketing

The LatticeXP devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits, which allows easy integration with the rest of the system. These capabilities make the LatticeXP ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The LatticeXP “C” devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced by up to three orders of magnitude during periods of system inactivity. Entry and exit to Sleep Mode is controlled by the SLEEPN pin.

During Sleep Mode, the FPGA logic is non-operational, registers and EBR contents are not maintained and I/Os are tri-stated. Do not enter Sleep Mode during device programming or configuration operation. In Sleep Mode, power supplies can be maintained in their normal operating range, eliminating the need for external switching of power supplies. Table 2-9 compares the characteristics of Normal, Off and Sleep Modes.

Table 2-9. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <100mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	Off	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up typically in the order of 10µA along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to V_{CC} is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically the device enters Sleep Mode several hundred ns after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet show a detailed timing diagram.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeXP family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeXP devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeXP devices contain two possible ports that can be used for device configuration and programming. The test access port (TAP), which supports serial configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The non-volatile memory in the LatticeXP can be configured in three different modes:

- In sysCONFIG mode via the sysCONFIG port. Note this can also be done in background mode.
- In 1532 mode via the 1149.1 port.
- In background mode via the 1149.1 port. This allows the device to be operated while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- In 1532 mode via the 1149.1 port SRAM direct configuration.
- In sysCONFIG mode via the sysCONFIG port SRAM direct configuration.

Lattice Semiconductor Corporation

LatticeXP Family Data Sheet DC and Switching Characteristics

November 2007 **Data Sheet DS1001**

Absolute Maximum Ratings[1, 2, 3, 4]

	XPE (1.2V)	XPC (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCP}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied[5]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied [5]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (Ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions outside of those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. All chip grounds are connected together to a common package GND plane.
5. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[3]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCP}	Supply Voltage for PLL for 1.2V Devices	1.14	1.26	V
	Supply Voltage for PLL for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[4]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[1, 2]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	85	C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	0	85	C

1. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as $V_{CCAUX.}$ For the XPE devices (1.2V V_{CC}), if V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}.
2. See recommended voltages by I/O standard in subsequent table.
3. The system designer must ensure that the FPGA design stays within the specified junction temperature and package thermal capabilities of the device based on the expected operating frequency, activity factor and environment conditions of the system.
4. V_{CCAUX} ramp rate must not exceed 30mV/µs during power up when transitioning between 0V and 3.3V.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LFXP3E	15	mA
		LFXP6E	20	mA
		LFXP10E	35	mA
		LFXP15E	45	mA
		LFXP20E	55	mA
		LFXP3C	35	mA
		LFXP6C	40	mA
		LFXP10C	70	mA
		LFXP15C	80	mA
		LFXP20C	90	mA
I_{CCP}	PLL Power Supply (per PLL)	All	8	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	22	mA
		LFXP6E/C	22	mA
		LFXP10E/C	30	mA
		LFXP15E/C	30	mA
		LFXP20E/C	30	mA
I_{CCIO}	Bank Power Supply[6]	All	2	mA
I_{CCJ}	V_{CCJ} Power Supply	All	1	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the VCCIO or GND.
3. Frequency 0MHz.
4. User pattern: blank.
5. T_A=25°C, power supplies at nominal voltage.
6. Per bank.

sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV ≤ V_{THD}	$V_{THD}/2$	1.2	1.8	V
		200mV ≤ V_{THD}	$V_{THD}/2$	1.2	1.9	V
		350mV ≤ V_{THD}	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

Figure 3-2. BLVDS Multi-point Output Example

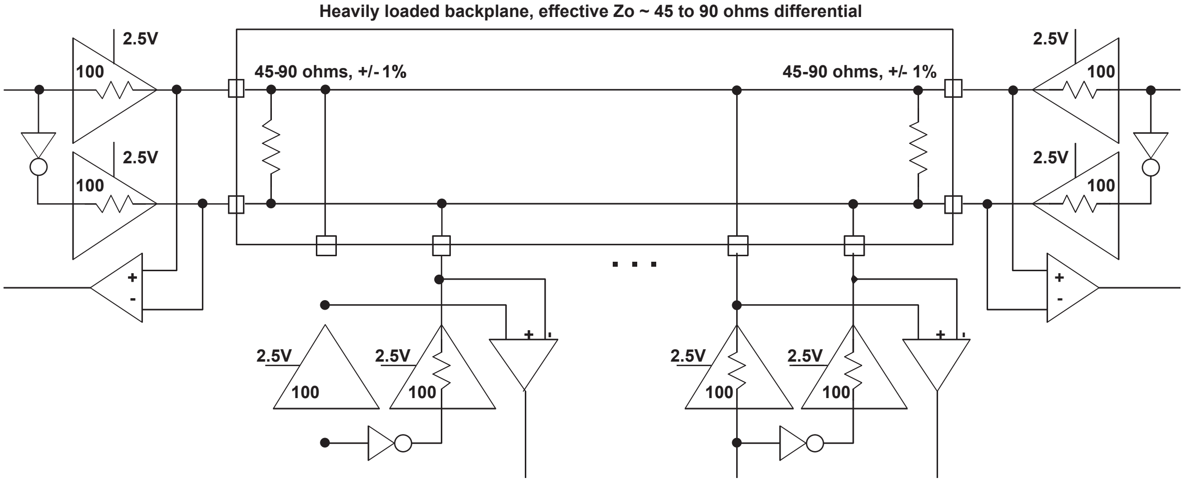


Table 3-2. BLVDS DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Typical		Units
		Zo = 45	Zo = 90	
Z_{OUT}	Output impedance	100	100	ohms
R_{TLEFT}	Left end termination	45	90	ohms
R_{TRIGHT}	Right end termination	45	90	ohms
V_{OH}	Output high voltage	1.375	1.48	V
V_{OL}	Output low voltage	1.125	1.02	V
V_{OD}	Output differential voltage	0.25	0.46	V
V_{CM}	Output common mode voltage	1.25	1.25	V
I_{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

Timing Diagrams

PFU Timing Diagrams

Figure 3-6. Slice Single/Dual Port Write Cycle Timing

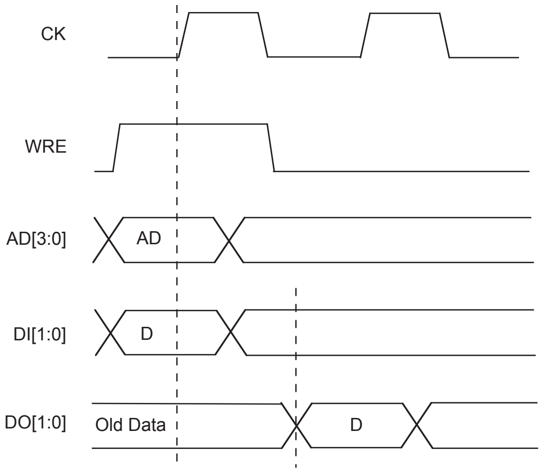
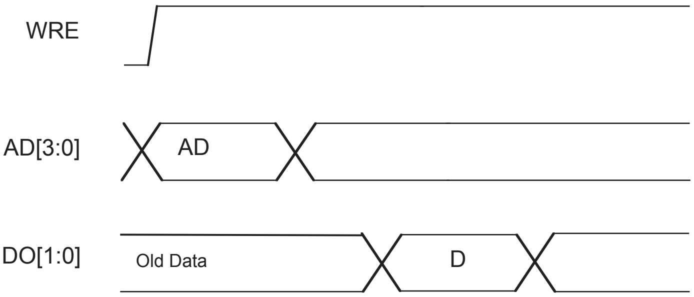


Figure 3-7. Slice Single /Dual Port Read Cycle Timing



LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
93	PR9A	2	T	PCLKT2_0	PR12A	2	T	PCLKT2_0
94	PR8B	2	C	RUM0_PLLC_IN_A	PR8B	2	C	RUM0_PLLC_IN_A
95	PR8A	2	T	RUM0_PLLT_IN_A	PR8A	2	T	RUM0_PLLT_IN_A
96	PR7B	2	C[3]	-	PR7B	2	C[3]	-
97	PR7A	2	T[3]	DQS	PR7A	2	T[3]	DQS
98	VCCIO2	2	-	-	VCCIO2	2	-	-
99	PR6B	2	-	VREF1_2	PR6B	2	-	VREF1_2
100	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
101	GNDIO2	2	-	-	GNDIO2	2	-	-
102	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
103	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A
104	PR2B	2	C[3]	-	PR2B	2	C[3]	-
105	PR2A	2	T[3]	-	PR2A	2	T[3]	-
106	VCCAUX	-	-	-	VCCAUX	-	-	-
107	TDO	-	-	-	TDO	-	-	-
108	VCCJ	-	-	-	VCCJ	-	-	-
109	TDI	-	-	-	TDI	-	-	-
110	TMS	-	-	-	TMS	-	-	-
111	TCK	-	-	-	TCK	-	-	-
112	VCC	-	-	-	VCC	-	-	-
113	PT25A	1	-	VREF1_1	PT28A	1	-	VREF1_1
114	PT24A	1	-	-	PT27A	1	-	-
115	PT23A	1	-	D0	PT26A	1	-	D0
116	PT22B	1	C	D1	PT25B	1	C	D1
117	PT22A	1	T	VREF2_1	PT25A	1	T	VREF2_1
118	PT21A	1	-	D2	PT24A	1	-	D2
119	VCCIO1	1	-	-	VCCIO1	1	-	-
120	PT20B	1	-	D3	PT23B	1	-	D3
121	GNDIO1	1	-	-	GNDIO1	1	-	-
122	PT17A	1	-	D4	PT20A	1	-	D4
123	PT16A	1	-	D5	PT19A	1	-	D5
124	PT15B	1	C	D6	PT18B	1	C	D6
125	PT15A	1	T	-	PT18A	1	T	-
126	PT14B	1	-	D7	PT17B	1	-	D7
127	GND	-	-	-	GND	-	-	-
128	PT13B	0	C	BUSY	PT16B	0	C	BUSY
129	PT13A	0	T	CS1N	PT16A	0	T	CS1N
130	PT12B	0	C	PCLKC0_0	PT15B	0	C	PCLKC0_0
131	PT12A	0	T	PCLKT0_0	PT15A	0	T	PCLKT0_0
132	PT11B	0	C	-	PT14B	0	C	-
133	VCCIO0	0	-	-	VCCIO0	0	-	-
134	PT11A	0	T	DQS	PT14A	0	T	DQS
135	PT9A	0	-	DOUT	PT12A	0	-	DOUT
136	GNDIO0	0	-	-	GNDIO0	0	-	-
137	PT8A	0	-	WRITEN	PT11A	0	-	WRITEN
138	PT7A	0	-	VREF1_0	PT10A	0	-	VREF1_0

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA

	LFXP6				LFXP10			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
C2	PROGRAMN	7	-	-	PROGRAMN	7	-	-
C1	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL3A	7	T	LUM0_PLLT_FB_A	PL3A	7	T	LUM0_PLLT_FB_A
D3	PL3B	7	C	LUM0_PLLC_FB_A	PL3B	7	C	LUM0_PLLC_FB_A
D1	PL2A	7	T[3]	-	PL5A	7	-	-
E2	PL5A	7	-	VREF1_7	PL6B	7	-	VREF1_7
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E1	PL7A	7	T[3]	DQS	PL7A	7	T[3]	DQS
F1	PL7B	7	C[3]	-	PL7B	7	C[3]	-
E3	PL12A	7	T	-	PL8A	7	T	-
F4	PL12B	7	C	-	PL8B	7	C	-
F3	PL4A	7	T[3]	-	PL9A	7	T[3]	-
F2	PL4B	7	C[3]	-	PL9B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G1	PL2B	7	C[3]	-	PL11B	7	-	-
G3	PL8A	7	T	LUM0_PLLT_IN_A	PL12A	7	T	LUM0_PLLT_IN_A
G2	PL8B	7	C	LUM0_PLLC_IN_A	PL12B	7	C	LUM0_PLLC_IN_A
H1	PL9A	7	T[3]	-	PL13A	7	T[3]	-
H2	PL9B	7	C[3]	-	PL13B	7	C[3]	-
G4	PL6B	7	-	VREF2_7	PL14A	7	-	VREF2_7
G5	PL14A	7	-	-	PL15B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J1	PL11A	7	T[3]	-	PL16A	7	T[3]	DQS
J2	PL11B	7	C[3]	-	PL16B	7	C[3]	-
H3	PL13A	7	T[3]	-	PL18A	7	T[3]	-
J3	PL13B	7	C[3]	-	PL18B	7	C[3]	-
H4	VCCP0	-	-	-	VCCP0	-	-	-
H5	GNDP0	-	-	-	GNDP0	-	-	-
K1	PL17A	6	T	PCLKT6_0	PL20A	6	T	PCLKT6_0
K2	PL17B	6	C	PCLKC6_0	PL20B	6	C	PCLKC6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
J4	PL15B	6	-	-	PL22A	6	-	-
J5	PL22A	6	-	VREF1_6	PL23B	6	-	VREF1_6
L1	PL16A	6	T[3]	-	PL24A	6	T[3]	DQS
L2	PL16B	6	C[3]	-	PL24B	6	C[3]	-
M1	PL18A	6	T[3]	-	PL25A	6	T	LLM0_PLLT_IN_A
M2	PL18B	6	C[3]	-	PL25B	6	C	LLM0_PLLC_IN_A
K3	PL19A	6	T[3]	-	PL26A	6	T[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L3	PL19B	6	C[3]	-	PL26B	6	C[3]	-
L4	PL21A	6	T[3]	-	PL28A	6	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP6				LFXP10			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
C2	PROGRAMN	7	-	-	PROGRAMN	7	-	-
C1	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
D3	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
D1	PL9A	7	-	-	PL9A	7	-	-
E2	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
E1	PL11A	7	T^3	DQS	PL11A	7	T^3	DQS
F1	PL11B	7	C^3	-	PL11B	7	C^3	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E3	PL12A	7	T	-	PL12A	7	T	-
F4	PL12B	7	C	-	PL12B	7	C	-
F3	PL13A	7	T^3	-	PL13A	7	T^3	-
F2	PL13B	7	C^3	-	PL13B	7	C^3	-
G1	PL15B	7	-	-	PL15B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G3	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
G2	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
H1	PL17A	7	T^3	-	PL17A	7	T^3	-
H2	PL17B	7	C^3	-	PL17B	7	C^3	-
G4	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
G5	PL19B	7	-	-	PL19B	7	-	-
J1	PL20A	7	T^3	DQS	PL20A	7	T^3	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J2	PL20B	7	C^3	-	PL20B	7	C^3	-
H3	PL22A	7	T^3	-	PL22A	7	T^3	-
J3	PL22B	7	C^3	-	PL22B	7	C^3	-
H4	VCCP0	-	-	-	VCCP0	-	-	-
H5	GNDP0	-	-	-	GNDP0	-	-	-
K1	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K2	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
J4	PL26A	6	-	-	PL30A	6	-	-
J5	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
L1	PL28A	6	T^3	DQS	PL32A	6	T^3	DQS
L2	PL28B	6	C^3	-	PL32B	6	C^3	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
M1	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
M2	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
K3	PL30A	6	T^3	-	PL34A	6	T^3	-
L3	PL30B	6	C^3	-	PL34B	6	C^3	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F15	PR10B	2	-	-	PR10B	2	-	-
E15	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
F14	PR8B	2	C[3]	-	PR8B	2	C[3]	-
E14	PR8A	2	T[3]	-	PR8A	2	T[3]	-
D15	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
C15	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
-	GNDIO2	2	-	-	GNDIO2	2	-	-
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT40B	1	C	-	PT44B	1	C	-
B15	PT40A	1	T	-	PT44A	1	T	-
D12	PT39B	1	C	VREF1_1	PT43B	1	C	VREF1_1
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C11	PT39A	1	T	DQS	PT43A	1	T	DQS
A14	PT38B	1	-	-	PT42B	1	-	-
B13	PT37A	1	-	-	PT41A	1	-	-
F12	PT36B	1	C	-	PT40B	1	C	-
E11	PT36A	1	T	-	PT40A	1	T	-
A13	PT35B	1	C	-	PT39B	1	C	-
C13	PT35A	1	T	D0	PT39A	1	T	D0
C10	PT34B	1	C	D1	PT38B	1	C	D1
E10	PT34A	1	T	VREF2_1	PT38A	1	T	VREF2_1
A12	PT33B	1	C	-	PT37B	1	C	-
B12	PT33A	1	T	D2	PT37A	1	T	D2
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C12	PT32B	1	C	D3	PT36B	1	C	D3
A11	PT32A	1	T	-	PT36A	1	T	-
B11	PT31B	1	C	-	PT35B	1	C	-
D11	PT31A	1	T	DQS	PT35A	1	T	DQS
B9	PT30B	1	-	-	PT34B	1	-	-
D9	PT29A	1	-	D4	PT33A	1	-	D4
A10	PT28B	1	C	-	PT32B	1	C	-
B10	PT28A	1	T	D5	PT32A	1	T	D5
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D10	PT27B	1	C	D6	PT31B	1	C	D6

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
F4	PROGRAMN	7	-	-	PROGRAMN	7	-	-	PROGRAMN	7	-	-
G4	CCLK	7	-	-	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL2A	7	T[3]	-	PL6A	7	T[3]	-	PL6A	7	T[3]	-
D1	PL2B	7	C[3]	-	PL6B	7	C[3]	-	PL6B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
E2	PL3A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
E3	PL3B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
F3	PL4A	7	T[3]	-	PL8A	7	T[3]	-	PL8A	7	T[3]	-
F2	PL4B	7	C[3]	-	PL8B	7	C[3]	-	PL8B	7	C[3]	-
H4	PL5A	7	-	-	PL9A	7	-	-	PL9A	7	-	-
H3	PL6B	7	-	VREF1_7	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
G3	PL7A	7	T[3]	DQS	PL11A	7	T[3]	DQS	PL11A	7	T[3]	DQS
G2	PL7B	7	C[3]	-	PL11B	7	C[3]	-	PL11B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
F1	PL8A	7	T	-	PL12A	7	T	-	PL12A	7	T	-
E1	PL8B	7	C	-	PL12B	7	C	-	PL12B	7	C	-
J4	PL9A	7	T[3]	-	PL13A	7	T[3]	-	PL13A	7	T[3]	-
K4	PL9B	7	C[3]	-	PL13B	7	C[3]	-	PL13B	7	C[3]	-
G1	PL11A	7	T[3]	-	PL15A	7	T[3]	-	PL15A	7	T[3]	-
H2	PL11B	7	C[3]	-	PL15B	7	C[3]	-	PL15B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
J2	PL12A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
H1	PL12B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
J1	PL13A	7	T[3]	-	PL17A	7	T[3]	-	PL17A	7	T[3]	-
K2	PL13B	7	C[3]	-	PL17B	7	C[3]	-	PL17B	7	C[3]	-
K3	PL14A	7	-	VREF2_7	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
J3	PL15B	7	-	-	PL19B	7	-	-	PL19B	7	-	-
K1	PL16A	7	T[3]	DQS	PL20A	7	T[3]	DQS	PL20A	7	T[3]	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
L2	PL16B	7	C[3]	-	PL20B	7	C[3]	-	PL20B	7	C[3]	-
L3	PL17A	7	T	-	PL21A	7	T	-	PL21A	7	T	-
L4	PL17B	7	C	-	PL21B	7	C	-	PL21B	7	C	-
L1	PL18A	7	T[3]	-	PL22A	7	T[3]	-	PL22A	7	T[3]	-
M1	PL18B	7	C[3]	-	PL22B	7	C[3]	-	PL22B	7	C[3]	-
M2	VCCP0	-	-	-	VCCP0	-	-	-	VCCP0	-	-	-
N1	GNDP0	-	-	-	GNDP0	-	-	-	GNDP0	-	-	-
M3	PL19A	6	T[3]	-	PL23A	6	T[3]	-	PL27A	6	T[3]	-
M4	PL19B	6	C[3]	-	PL23B	6	C[3]	-	PL27B	6	C[3]	-
P1	PL20A	6	T	PCLKT6_0	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
N2	PL20B	6	C	PCLKC6_0	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
R1	PL21A	6	T[3]	-	PL25A	6	T[3]	-	PL29A	6	T[3]	-
P2	PL21B	6	C[3]	-	PL25B	6	C[3]	-	PL29B	6	C[3]	-
N3	PL22A	6	-	-	PL26A	6	-	-	PL30A	6	-	-
N4	PL23B	6	-	VREF1_6	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T1	PL24A	6	T[3]	DQS	PL28A	6	T[3]	DQS	PL32A	6	T[3]	DQS
R2	PL24B	6	C[3]	-	PL28B	6	C[3]	-	PL32B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
G9	VCC	-	-	-	VCC	-	-	-
H15	VCC	-	-	-	VCC	-	-	-
H8	VCC	-	-	-	VCC	-	-	-
J16	VCC	-	-	-	VCC	-	-	-
J7	VCC	-	-	-	VCC	-	-	-
K16	VCC	-	-	-	VCC	-	-	-
K17	VCC	-	-	-	VCC	-	-	-
K6	VCC	-	-	-	VCC	-	-	-
K7	VCC	-	-	-	VCC	-	-	-
N16	VCC	-	-	-	VCC	-	-	-
N17	VCC	-	-	-	VCC	-	-	-
N6	VCC	-	-	-	VCC	-	-	-
N7	VCC	-	-	-	VCC	-	-	-
P16	VCC	-	-	-	VCC	-	-	-
P7	VCC	-	-	-	VCC	-	-	-
R15	VCC	-	-	-	VCC	-	-	-
R8	VCC	-	-	-	VCC	-	-	-
T10	VCC	-	-	-	VCC	-	-	-
T13	VCC	-	-	-	VCC	-	-	-
T14	VCC	-	-	-	VCC	-	-	-
T9	VCC	-	-	-	VCC	-	-	-
U10	VCC	-	-	-	VCC	-	-	-
U13	VCC	-	-	-	VCC	-	-	-
G15	VCCAUX	-	-	-	VCCAUX	-	-	-
G16	VCCAUX	-	-	-	VCCAUX	-	-	-
G7	VCCAUX	-	-	-	VCCAUX	-	-	-
G8	VCCAUX	-	-	-	VCCAUX	-	-	-
H16	VCCAUX	-	-	-	VCCAUX	-	-	-
H7	VCCAUX	-	-	-	VCCAUX	-	-	-
R16	VCCAUX	-	-	-	VCCAUX	-	-	-
R7	VCCAUX	-	-	-	VCCAUX	-	-	-
T15	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-
T8	VCCAUX	-	-	-	VCCAUX	-	-	-
F11	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-
H10	VCCIO0	0	-	-	VCCIO0	0	-	-
H11	VCCIO0	0	-	-	VCCIO0	0	-	-
F12	VCCIO1	1	-	-	VCCIO1	1	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-
H12	VCCIO1	1	-	-	VCCIO1	1	-	-

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeXP Family Data Sheet
Ordering Information

December 2005 **Data Sheet DS1001**

Part Number Description

LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4FN388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3FN256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4FN256I	188	1.2V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4FN484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3FN388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4FN388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3FN256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4FN256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4FN484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3FN388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4FN388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3FN256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4FN256I	188	1.2V	-4	fpBGA	256	IND	19.7K